

ABSTRACT

The present invention relates to a waveguide structured package and a method of manufacturing the same. More particularly, there are provided a
5 waveguide structured package capable of preventing generation of parasitic components due to bonding wires and reducing the processing time to reduce the production cost of the waveguide structured package by providing a probe, a microstrip-waveguide transition portion and a microstrip
10 line within a semiconductor chip and thus making bonding wire unnecessary in manufacturing the waveguide structured package, and a method of manufacturing the waveguide structured package.